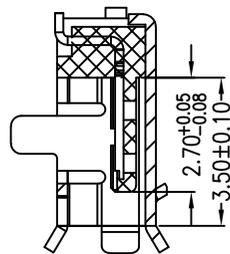
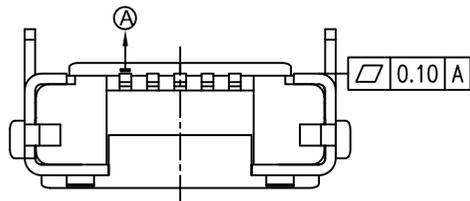
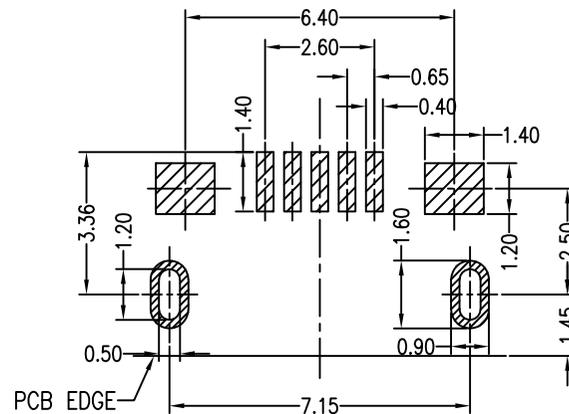
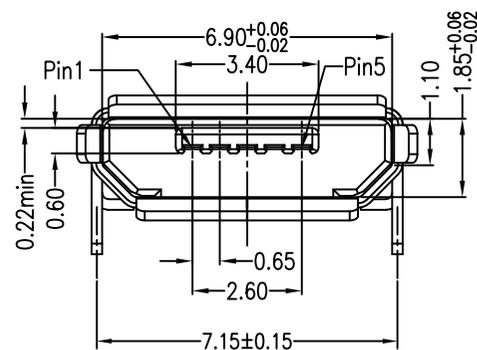
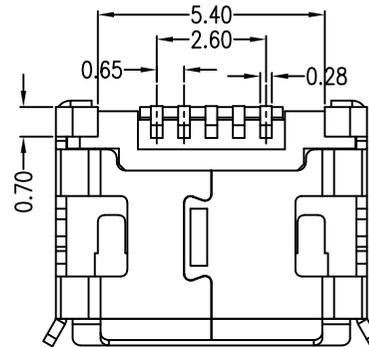
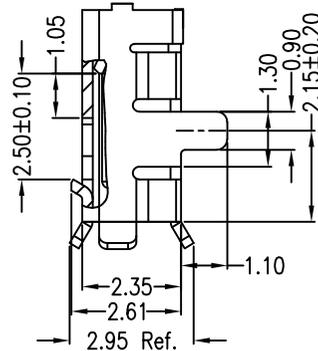
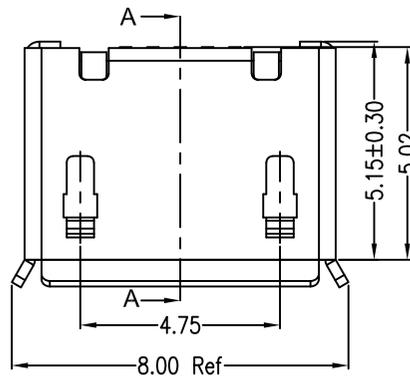


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2021/02/14	Ken Lin
A0.1			Add Note.	2022/08/01	Ken Lin
A0.2			Change Note.	2024/01/24	Ken Lin



SECTION A-A



RECOMMENDED PCB LAYOUT

PCB图仅供参考

Note:

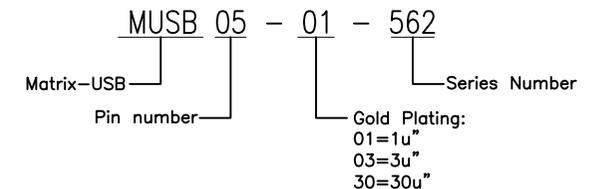
1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
Au 1u" min plated on the functional area of contact.
- 1.3 Shell: copper alloy,t=0.25mm (Matte Tin) $\triangle A0.1$
Au 1u" plated on solder area.
Ni 50u" min. Under plated over all.

2.Specification:

- 2.1 Current rating:1,5PIN 1.8A Max/2,3,4PIN 1A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 m Ω Max.
- 2.4 Insulation resistance: 100 M Ω Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.
- 2.7 Temperature range: -40°C~85°C $\triangle A0.2$

MATRIX PART NO:



Matrix Electronics Co.,Ltd

TOLERANCE: X:X ±0.15 X:XX ±0.10 X:XXX ±0.05 ANGLE: ±1°	DESIGN BY : Ken Lin	DATE : 2024/01/24	PART NAME: Micro USB 5P B Type Female	
	CHECKED BY: Hanson Huang	DATE : 2024/01/24	PART NO.	MUSB05-01-562
	APPROVED BY1: Richard Hsieh	DATE : 2024/01/24	MOLD NO.	NA
UNIT: mm [inch]	APPROVED BY2: Richard Hsieh	DATE : 2024/01/24	DRAW NO.	
SCALE:1:1 SIZE:A4			SHEET NO.	1 OF 1